



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of  
Takao OHNO, et al.

Serial No.: Not Yet

Group Art Unit: Not Yet  
Assigned  
Examiner: Not Yet  
Assigned

Filed: February 12, 2004

For: POLYMETAPHENYLENE ISOPHTHALAMIDE-BASED POLYMER POROUS  
FILM, PROCESS FOR ITS PRODUCTION AND BATTERY SEPARATOR

DECLARATION UNDER 37 C.F.R. 1.132

Assistant Commissioner of Patents and Trademarks,  
Alexandria, VA 22313-1450

Sir:

I, Susumu HONDA, c/o TEIJIN LIMITED, Iwakuni Research  
Center, 2-1, Hinodecho, Iwakuni-shi, Yamaguchi 740-0014,  
Japan do hereby declare:

That I am a co-inventor of the invention disclosed in  
the above-identified U.S. application (hereinafter referred  
to as "present application" for brevity) and I am one of the

conductors of all of the work reported in the examples including the comparative example in the specification of the present application, and the results obtained are as set forth therein; and

That, although there is no description in the specification of the present application, the density of the polymetaphenylene isophthalamide (relative viscosity = 1.8) used in Examples 1 to 7 of the present application was 1.338 g/cm<sup>3</sup>. This true density was determined for a film obtained by casting a dope of the polymetaphenylene isophthalamide onto a glass plate and removing the solvent used by heating only. This film-forming method is a method in which no coagulating bath is used and, thus, the resulting film is a dense (non-porous) film. Therefore, the above-mentioned density of the film is believed to be approximately equal to the true density of the polymer.

I, the undersigned declarant, declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and; further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001, of Title 18, of the United States Code, and that such willful false statements may jeopardize the

validity of the application or any patent issuing thereon.

Signed this 11th day of March , 2004

Susumu Honda

Susumu Honda